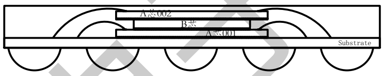
池州华宇电子科技股份有限公司
CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD

焊线图纸 Bonding Diagram

客户代码 Customer No.		线图号 Drawing No.		页码 Page
产品名称 Product Type		封装外型 PKG Type	BGA117(7.5X10.5X1.30-P0.8)	

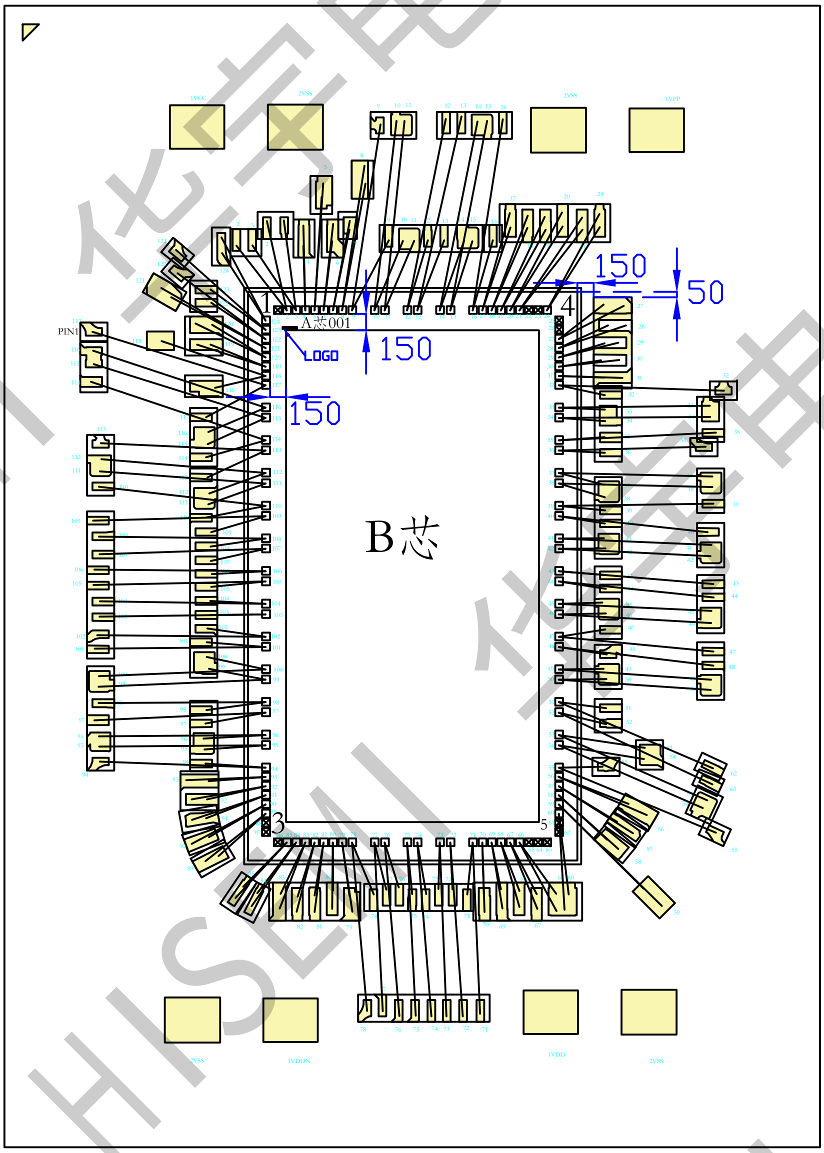
焊线种类 Wire Type	焊线直径(µm) Wire Diameter	焊线根数 NO. of wire	焊线总长(µm) Total wire length	最长线长(µm) Longest wire length	最短线长(µm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.
金丝 Au	20			1827	400	首选(Preferred)：KE-G1250 备选(Optional)：	BGA117(075105)1115001
客户图号 Customer drawing NO.							

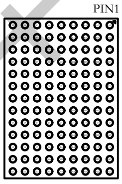


WB打线见附页

PIN1

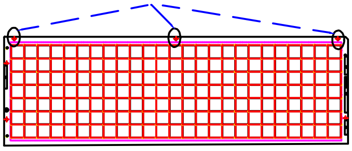
叠层芯片，注意打线精度，避免撞线！





底部示意图

框架传送方向（装片）：
L/F Direction（D/A）：上侧三个圆孔



实物图：

特殊说明 Special Instructions：

DB注意：
1.装片精度±50um;
2.以随工单要求按顺序装片，如：先装A芯001，再装B芯片，再装A芯002.

WB注意：
1.数字为不打线pad点个数；
2.先键合A芯001，再键合A芯002.

拟制 Prepared by		制图日期 Create Date		生效日期 Effective Date		客户确认签字/盖章：Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！
*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

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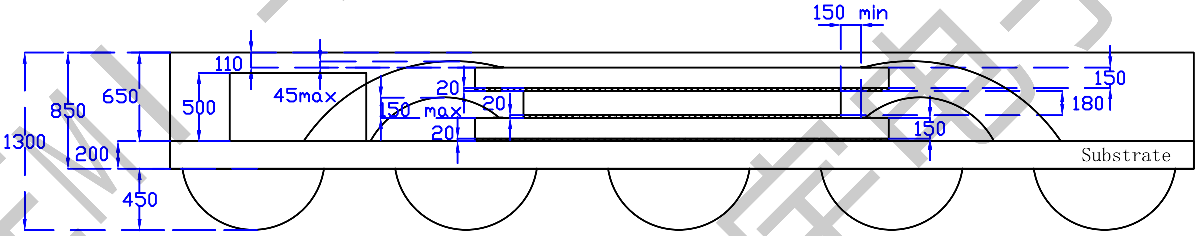

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